

Please add in the following claims:

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CLAIM 12: The semiconductor wafer processing system according to Claim 2, wherein:

the modules of each of the module groups are also arranged in a multi-layered fashion to form at least two module layers and have the same module type or a combination of different module types;

each of the module groups constitutes a station, together with feeding means; and

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a ~~feeding~~ ^{feeding} interface or buffer stocker is arranged between adjacent stations respectively associated with the module groups.

CLAIM 13: The semiconductor wafer processing system according to Claim 5, further comprising:

a stocker provided at the second interface arranged between a spinner, in which a baking process is carried out, and the stepper, the stocker having a plurality of stock compartments arranged in a multi-layered fashion and adapted to stock wafers completely processed by photoresist coating and developing processes; and a pair of wafers feeding arms arranged at opposite sides of the stocker, respectively, to stock wafers in the stock compartments of the stocker at the opposite sides of the stocker.

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CLAIM 14: The semiconductor wafer processing system according to Claim 6, further comprising:
a stocker provided at the second interface arranged between a spinner, in which a baking process is carried out, and the stepper, the stocker having a plurality of stock compartments arranged in a multi-layered fashion and adapted to stock wafers completely processed by photoresist coating and developing processes; and a pair of wafers feeding arms arranged at opposite sides of the stocker, respectively, to stock wafers in the stock compartments of the stocker at the opposite sides of the stocker.

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CLAIM 15: The semiconductor wafer processing system according to Claim 7, further comprising:
a stocker provided at the second interface arranged between a spinner, in which a baking process is carried out, and the stepper, the stocker having a plurality of stock compartments arranged in a multi-layered fashion and adapted to stock wafers completely processed by photoresist coating and developing processes; and a pair of wafers feeding arms arranged at opposite sides of the stocker, respectively, to stock wafers in the stock compartments of the stocker at the opposite sides of the stocker.

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CLAIM 16: The semiconductor wafer processing system according to Claim 8, further comprising:
a stocker provided at the second interface arranged between a spinner, in which a baking process is carried out, and the stepper, the stocker having a plurality of stock compartments arranged in a multi-layered fashion and adapted to stock wafers completely processed by photoresist coating and developing processes; and a pair of wafers feeding arms arranged at opposite sides of the stocker, respectively, to stock wafers in the stock compartments of the stocker at the opposite sides of the stocker.

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